Supplier Information Company name* Company name* Company name* Company unique ID Company unique ID Company name* Company unique ID	IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company name* Company unique ID Unique ID Authority Response Date* 2024-04-18 Contact Name	752-21.1										als and Mf	Information	on		
Semilar Semi	upplier Informa	ation													
Title - Contact Name Product Envisements Produ	Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
Product Envisor Compliance Unitorized Representative* Title - Representative Tompliance NA Product Envisor Compliance NA Product-Env-Stewards Onsemi.com Na Product-Env-Stewards Onsemi.com Na Product-Env-Stewards Onsemi.com Na Nanufacturing Site Weight* UOM Unit 1 107.2528 mg Each Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy 1-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed Outline Stewards O	nsemi											2024-04-18			
Title - Representative Product Envi- Stewards Product Envi- Compliance NA Product Envi- Stewards Product Envi- Compliance NA Product Envi- Stewards Product Envi- Compliance NA Product Envi- Stewards Product Envi Stewards Product Envi Stewards Product Envi Stewards Product En	Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product Envisor Compliance Requester Item Number Mfr Item Numb	Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative*			Title - Representative			I	Phone - Representative*			Email - Representative*				
NTMFS5832NLT1G NFET SO8FL 40V 110A 4.2MO 2024-04-18 MY1 107.2528 mg Each	Product-Env-Stewar	rds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds Somments Evel 1 - maximum time at peak temperature during soldering is 10-30 seconds	Requester	Requester Item Number Mfr Ite		em Number Mfr Item Name				Effective Date	Version	N	Manufacturing Site		eight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 Comments Revel 1 - maximum time at peak temperature during soldering is 10-30 seconds			NTMFS5	832NLT1G	NFET SO8FL 40V	110A 4.2MO		2024-04-18		MY1		10	07.2528	mg	Each
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or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier neter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provid											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting tempe	erature type solders (i.e. lead based solder	alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	13.512	mg	Supplier	Zinc (Zn)	7440-66-6		0.0162	mg
			Supplier	Iron (Fe)	7439-89-6		0.3175	mg
			Supplier	Copper (Cu)	7440-50-8		13.1742	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0041	mg
Die	0.727	mg	Supplier	Silicon (Si)	7440-21-3		0.727	mg
Die Attach Solder	1.4993	mg	Supplier	Silver (Ag)	7440-22-4		0.0375	mg
			A	Lead (Pb)	7439-92-1	7a	1.3869	mg
			Supplier	Tin (Sn)	7440-31-5		0.075	mg
Lead Frame	42.5398	mg	Supplier	Silver (Ag)	7440-22-4		0.0255	mg
			Supplier	Iron (Fe)	7439-89-6		0.0425	mg
			Supplier	Copper (Cu)	7440-50-8		42.459	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0128	mg
Mold Compound-Black	48.7198	mg		Epoxy resin	proprietary data		3.654	mg
			Supplier	Phenolic Resin	Proprietary Data		1.218	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.654	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2436	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.9502	mg
Plating	0.2183	mg	Supplier	Tin (Sn)	7440-31-5		0.2183	mg
Wire Bond - Cu	0.0366	mg	Supplier	Copper (Cu)	7440-50-8		0.0366	mg